



TITLE: THINNED DIE INTEGRATED CIRCUIT PACKAGE

INVENTORS NAME: Cheng-Yi Liu et al.

SERIAL NO.: 10/036389

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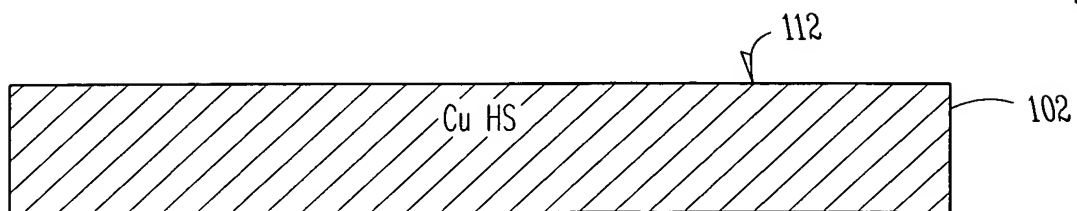


Fig. 1

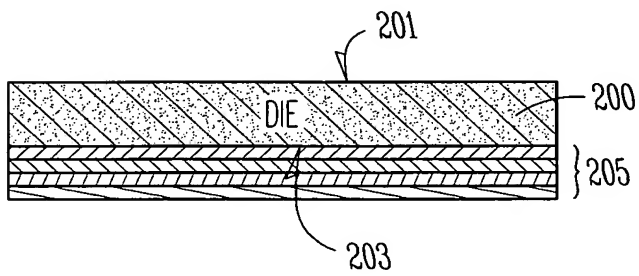


Fig. 2

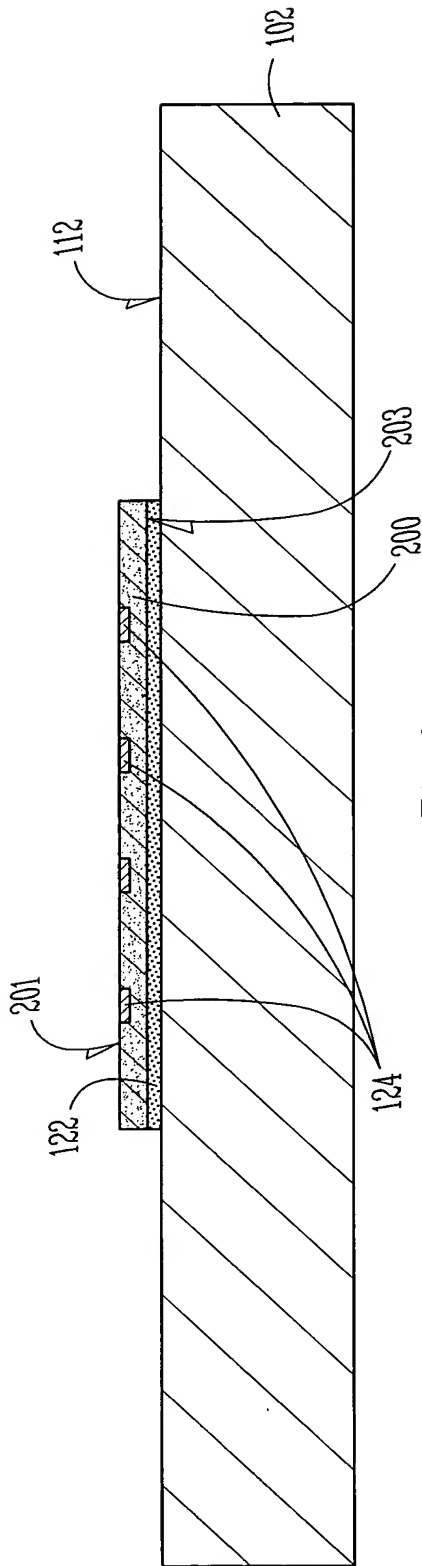


Fig. 3

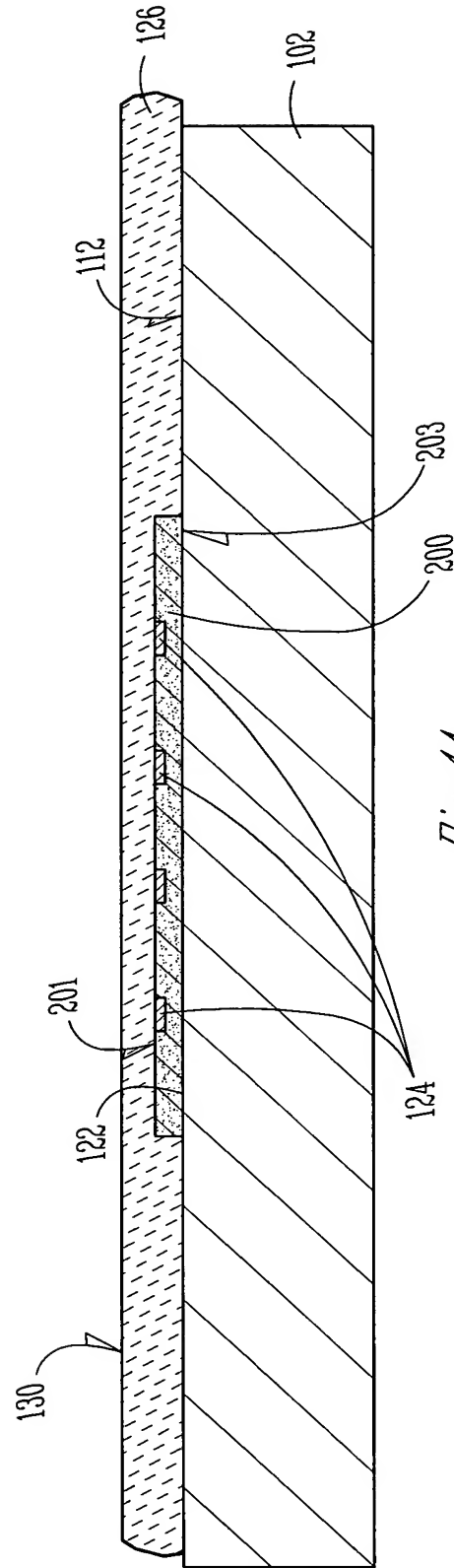


Fig. 4A

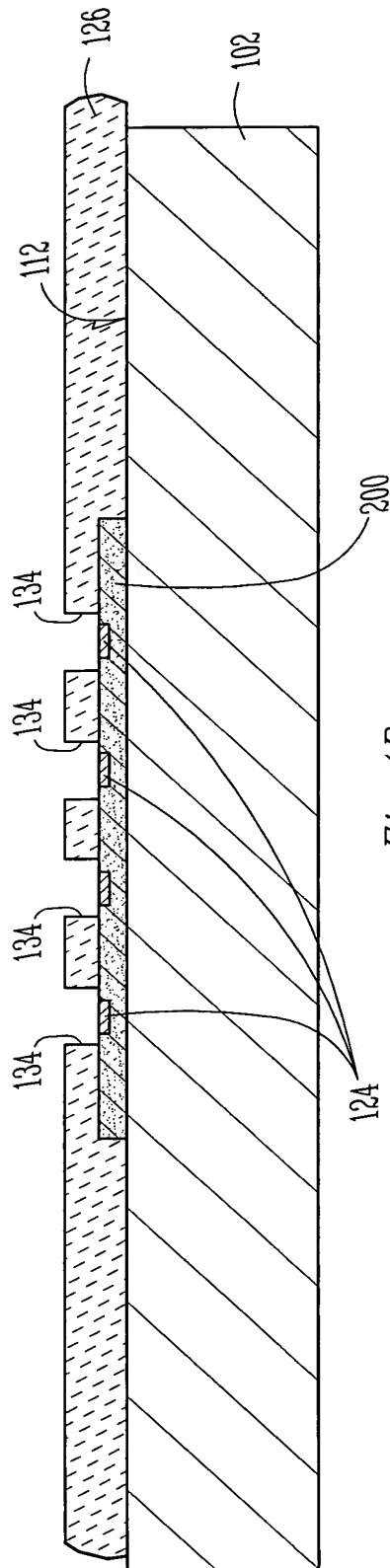


Fig. 4B

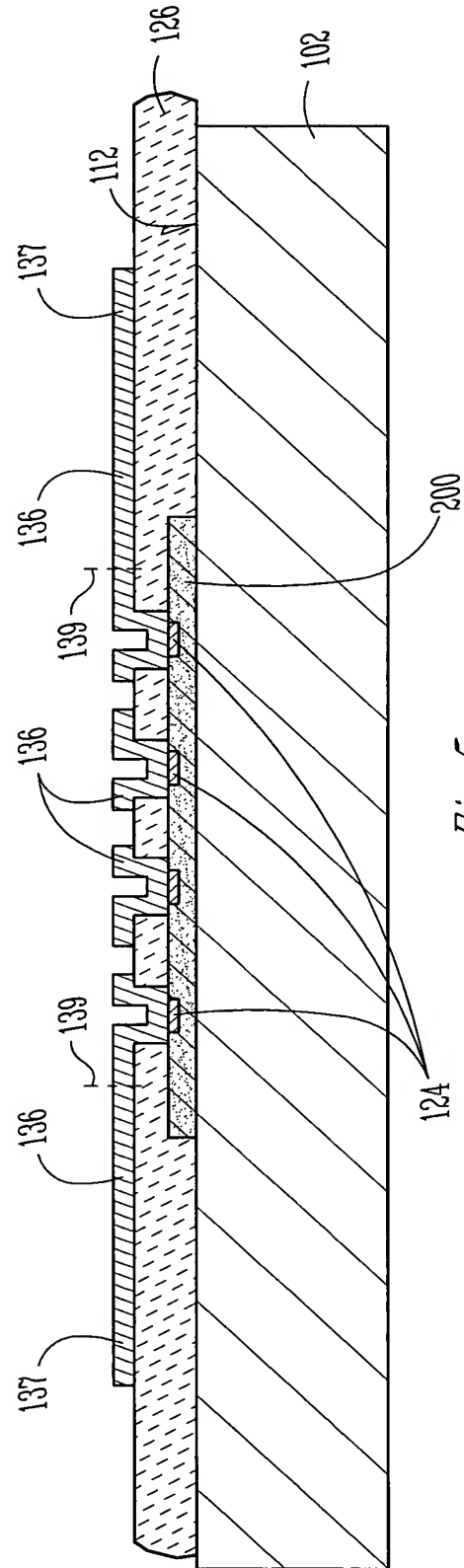


Fig. 5

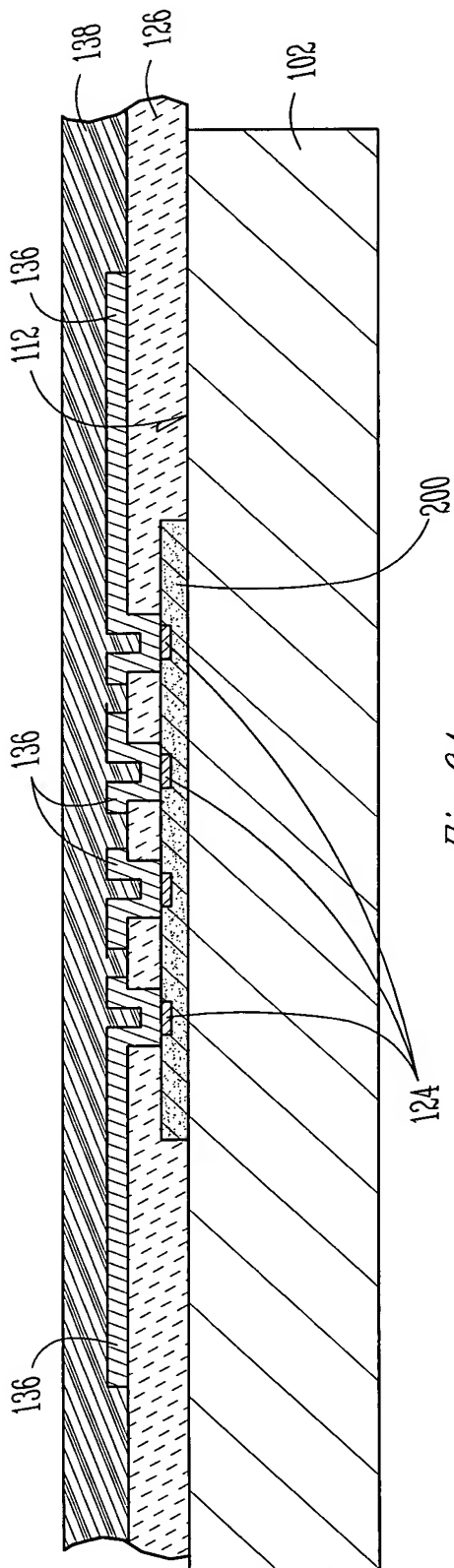


Fig. 6A

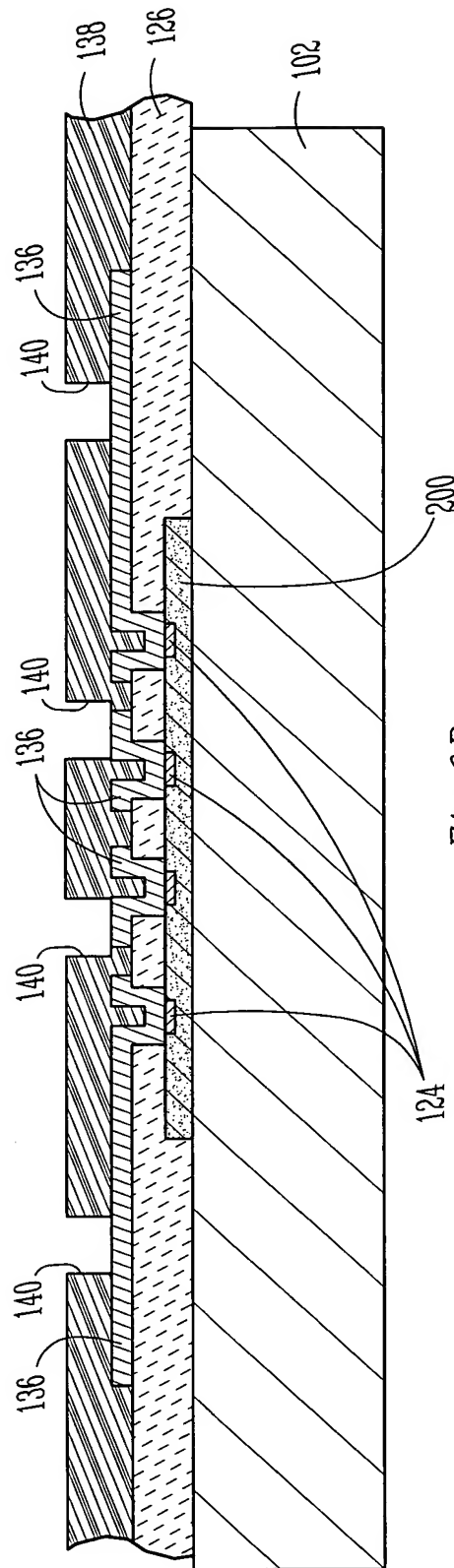


Fig. 6B

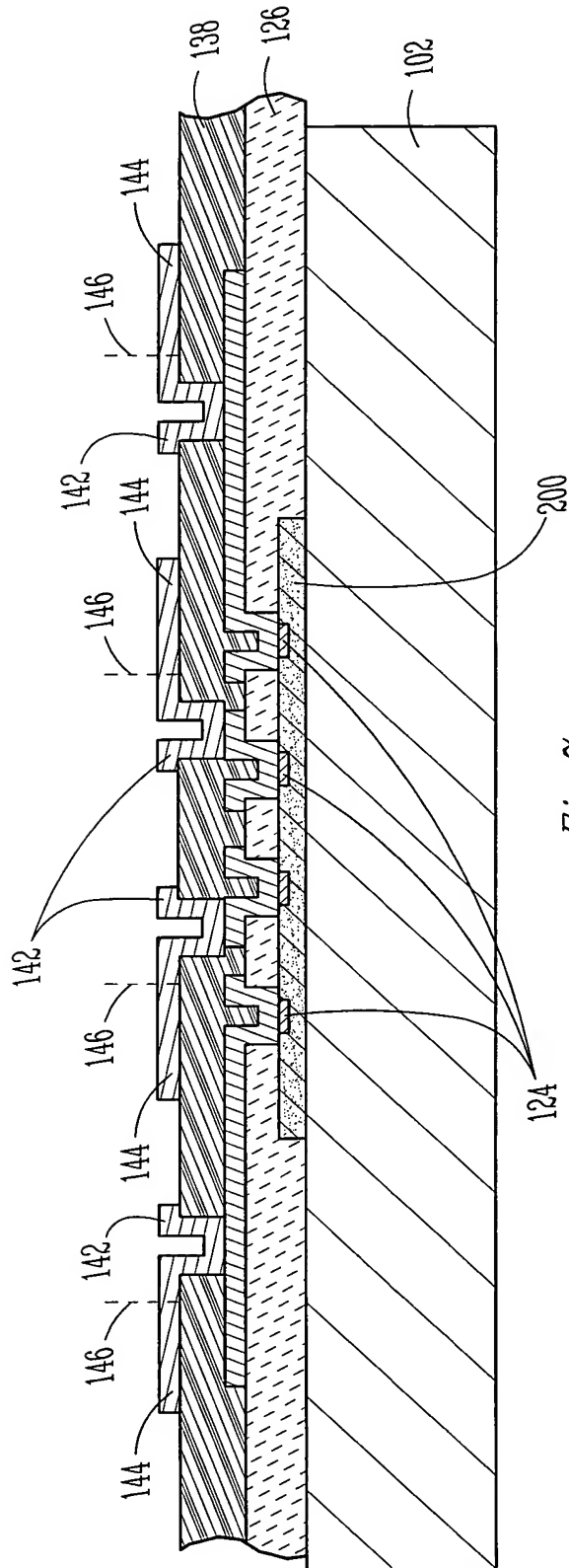


Fig. 7

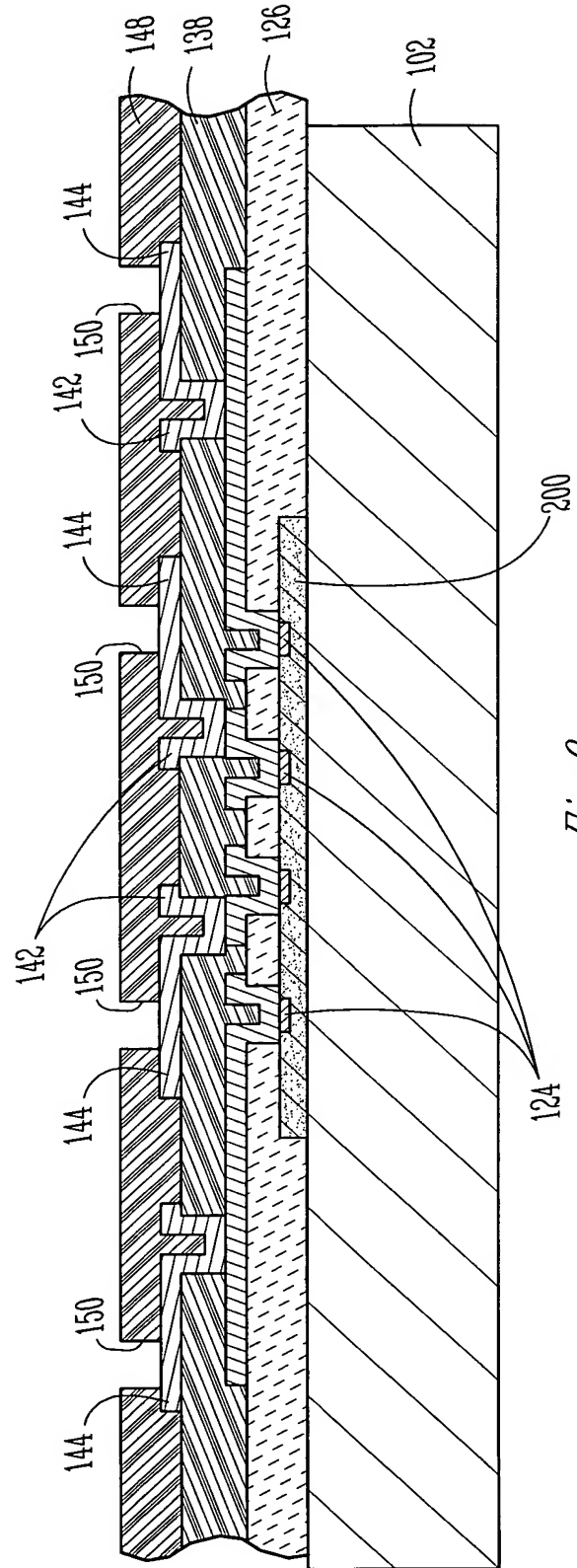


Fig. 8

Fig. 9



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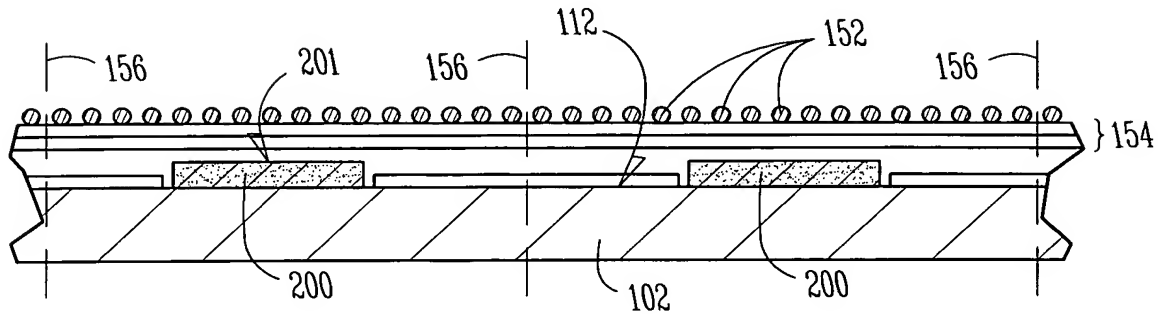


Fig. 10A

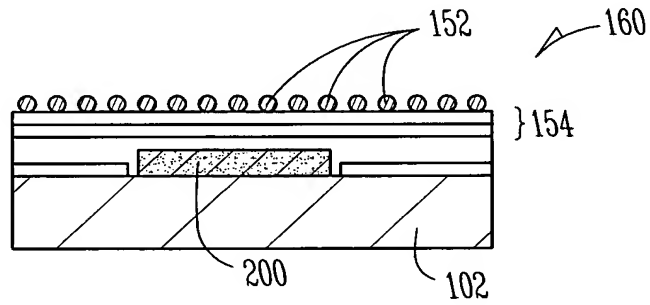


Fig. 10B

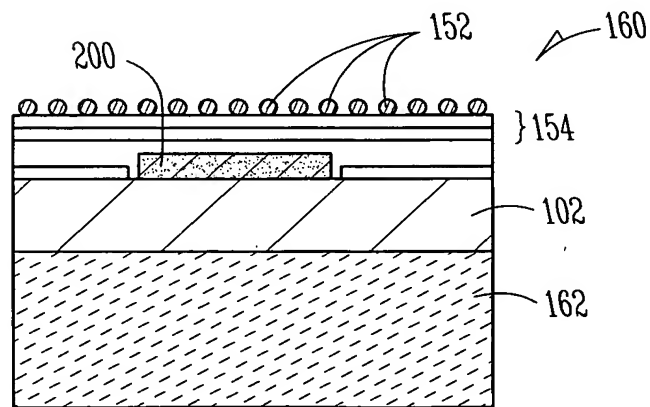


Fig. 11

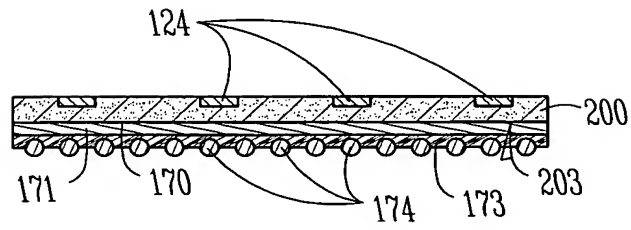


Fig. 12A

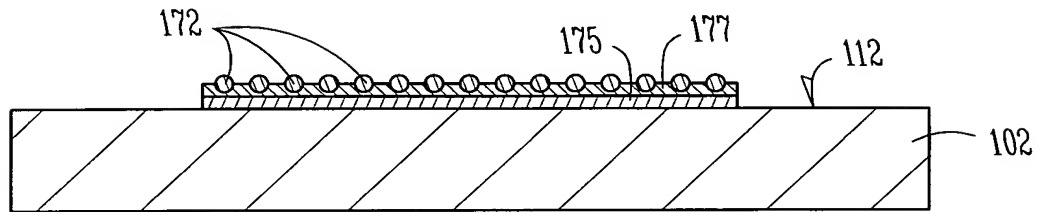


Fig. 12B

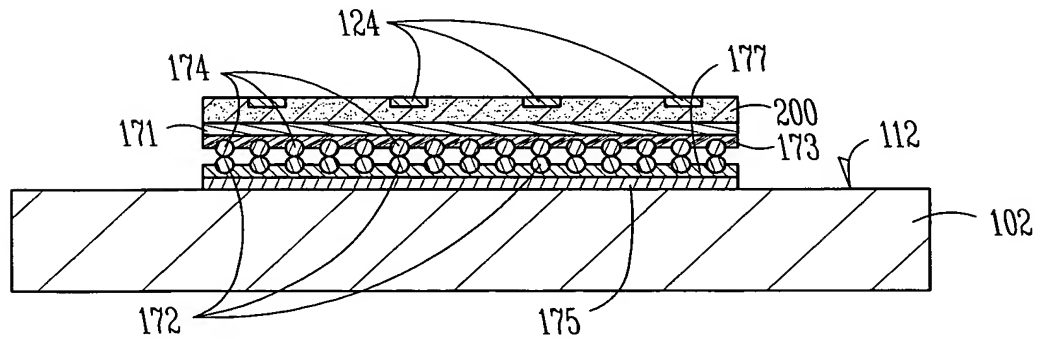


Fig. 12C

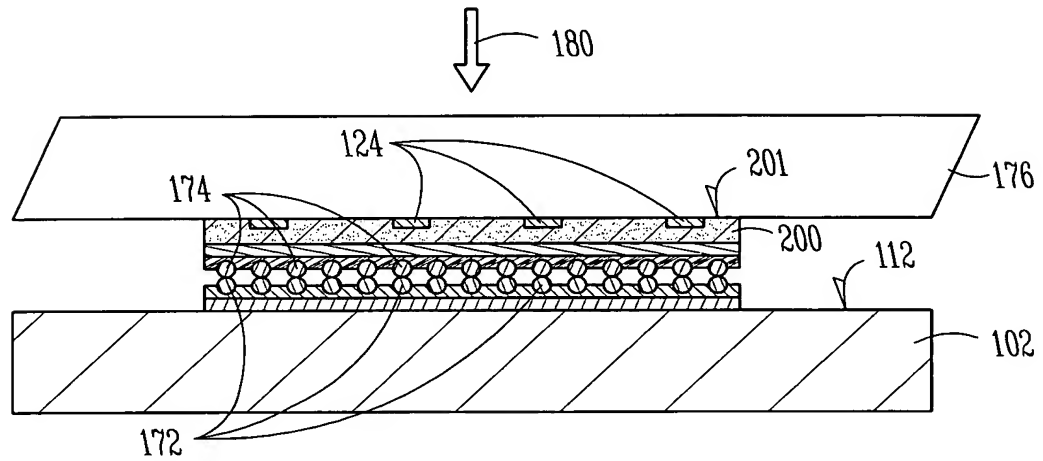


Fig. 13

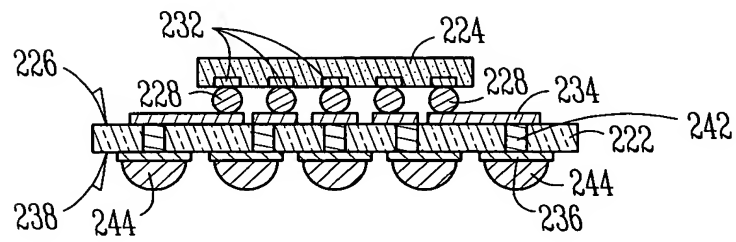


Fig. 16
(Prior Art)

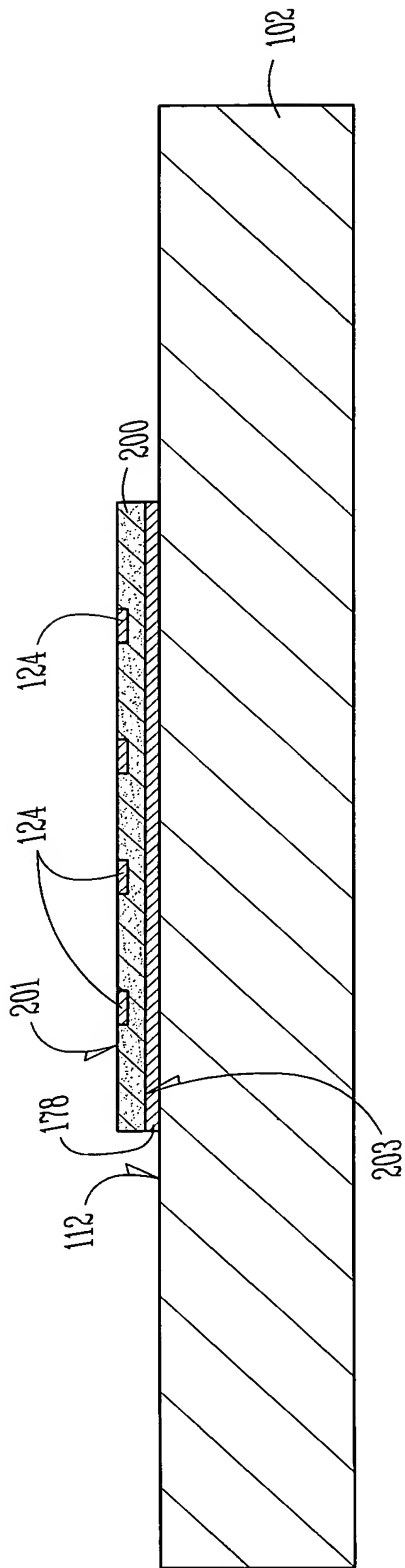


Fig. 14

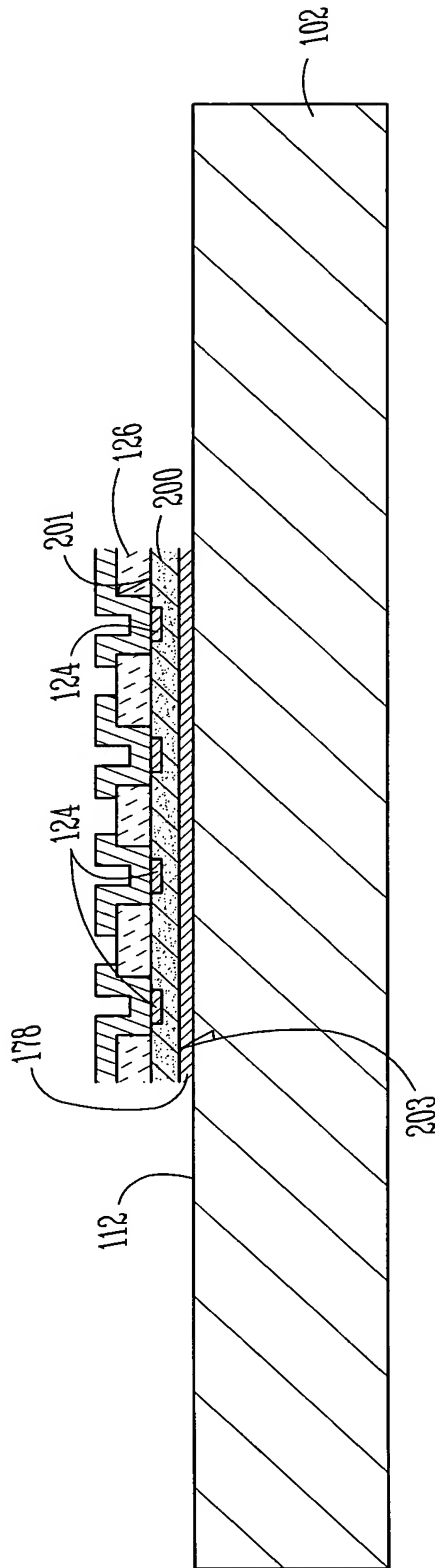


Fig. 15